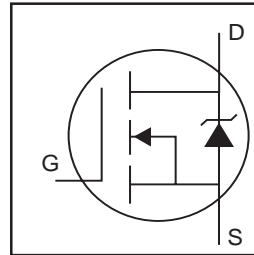


# IRLBA1304PbF

HEXFET® Power MOSFET

- Logic-Level Gate Drive
- Ultra Low On-Resistance
- Same outline as TO-220
- 50% greater current in typ. application conditions vs. TO-220
- Fully Avalanche Rated
- Purchase IRLBA1304/P for solder plated option.
- Lead-Free

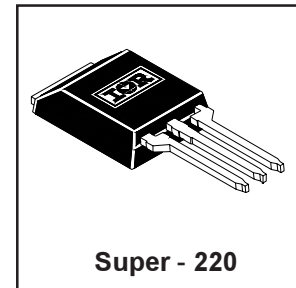


$V_{DSS} = 40V$
$R_{DS(on)} = 0.004\Omega$
$I_D = 185A$ Ⓢ

## Description

The HEXFET® is the most popular power MOSFET in the world.

This particular HEXFET® is in the Super220™ and has the same outline and pinout as the industry standard TO-220. It has increased current handling capability over both the TO-220 and the much larger TO-247 package. This makes it ideal to reduce component count in multiparalleled TO-220 applications, reduce system power dissipation, upgrade existing designs or have TO-247 performance in a TO-220 outline. This package has also been designed to meet automotive qualification standard Q101.



## Absolute Maximum Ratings

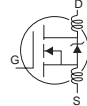
	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	185, pkg limited to 95A*	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	130, pkg limited to 95A*	
$I_{DM}$	Pulsed Drain Current Ⓣ	740	
$P_D @ T_C = 25^\circ C$	Power Dissipation	300	W
	Linear Derating Factor	2.0	W/°C
$V_{GS}$	Gate-to-Source Voltage	$\pm 16$	V
$E_{AS}$	Single Pulse Avalanche EnergyⓉ	1160	mJ
$I_{AR}$	Avalanche CurrentⓉ	100	A
$E_{AR}$	Repetitive Avalanche EnergyⓉ	30	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ Ⓣ	5.0	V/ns
$T_J$	Operating Junction and	-55 to + 175	°C
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds		
	Recommended clip force	20	N

## Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	0.5	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.5	—	
$R_{\theta JA}$	Junction-to-Ambient	—	58	

\* Current capability in normal application, see Fig.9.  
[www.irf.com](http://www.irf.com)

## Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	40	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔV <sub>(BR)DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temp. Coefficient	—	0.043	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance	—	—	0.0040	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 110A ③
		—	—	0.0065		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 93 ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	1.0	—	—	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
g <sub>fs</sub>	Forward Transconductance	120	—	—	S	V <sub>DS</sub> = 25V, I <sub>D</sub> = 110A
I <sub>DSS</sub>	Drain-to-Source Leakage Current	—	—	25	μA	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V
		—	—	250		V <sub>DS</sub> = 32V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 150°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	—	—	100	nA	V <sub>GS</sub> = 16V
	Gate-to-Source Reverse Leakage	—	—	-100		V <sub>GS</sub> = -16V
Q <sub>g</sub>	Total Gate Charge	—	—	140	nC	I <sub>D</sub> = 110A
Q <sub>gs</sub>	Gate-to-Source Charge	—	—	39		V <sub>DS</sub> = 32V
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge	—	—	79		V <sub>GS</sub> = 4.5V, See Fig. 6 and 13 ④
t <sub>d(on)</sub>	Turn-On Delay Time	—	21	—	—	V <sub>DD</sub> = 20V
t <sub>r</sub>	Rise Time	—	350	—		I <sub>D</sub> = 110A
t <sub>d(off)</sub>	Turn-Off Delay Time	—	45	—		R <sub>G</sub> = 0.9Ω
t <sub>f</sub>	Fall Time	—	103	—		R <sub>D</sub> = 0.18Ω, See Fig. 10 ④
L <sub>D</sub>	Internal Drain Inductance	—	2.0	—	nH	Between lead, 6mm (0.25in.) from package and center of die contact
L <sub>S</sub>	Internal Source Inductance	—	5.0	—		
C <sub>iss</sub>	Input Capacitance	—	7660	—	pF	V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance	—	2150	—		V <sub>DS</sub> = 25V
C <sub>rss</sub>	Reverse Transfer Capacitance	—	460	—		f = 1.0MHz, See Fig. 5

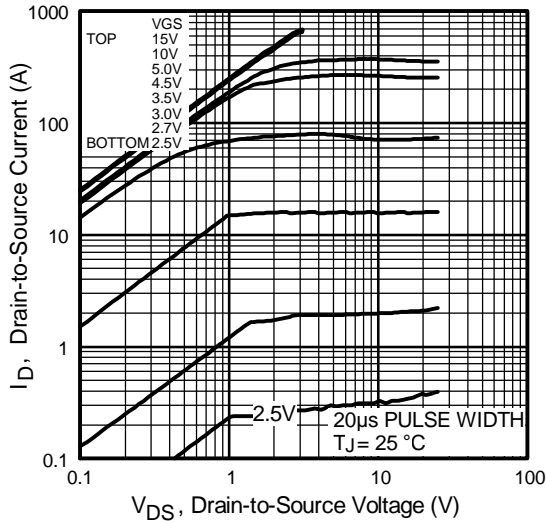
## Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	185*	A	MOSFET symbol showing the integral reverse p-n junction diode.
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①	—	—	740		
V <sub>SD</sub>	Diode Forward Voltage	—	—	1.3	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 110A, V <sub>GS</sub> = 0V ④
t <sub>rr</sub>	Reverse Recovery Time	—	100	150	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 110A
Q <sub>rr</sub>	Reverse Recovery Charge	—	250	380	nC	di/dt = 100A/μs ④
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> )				

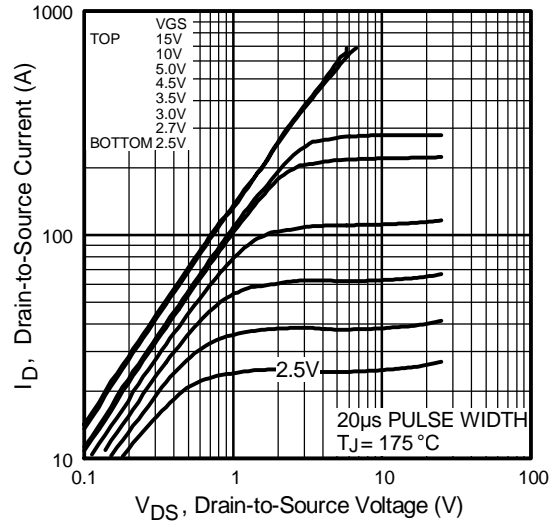
### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )
- ② Starting T<sub>J</sub> = 25°C, L = 230μH  
R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 100A. (See Figure 12)

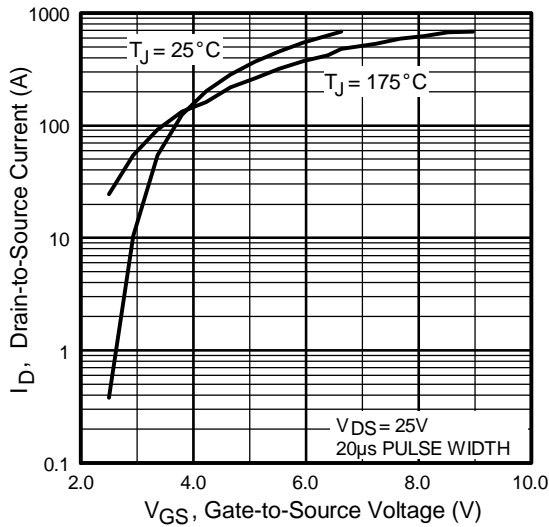
- ③ I<sub>SD</sub> ≤ 110A, di/dt ≤ 170A/μs, V<sub>DD</sub> ≤ V<sub>(BR)DSS</sub>,  
T<sub>J</sub> ≤ 175°C
- ④ Pulse width ≤ 300μs; duty cycle ≤ 2%.



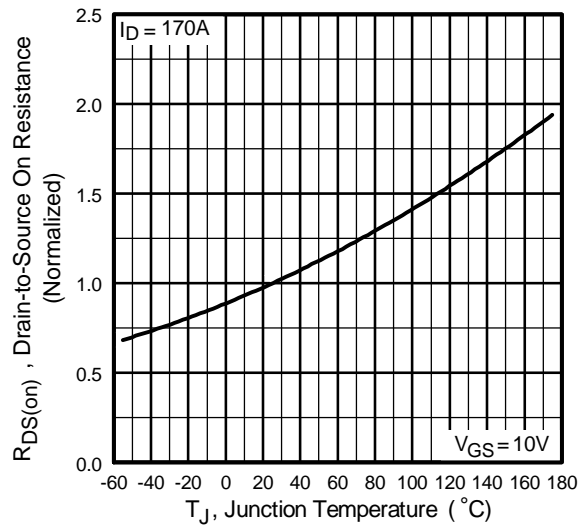
**Fig 1.** Typical Output Characteristics



**Fig 2.** Typical Output Characteristics



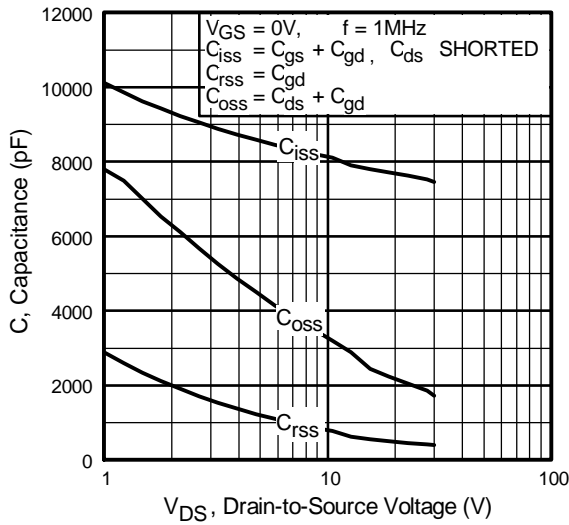
**Fig 3.** Typical Transfer Characteristics



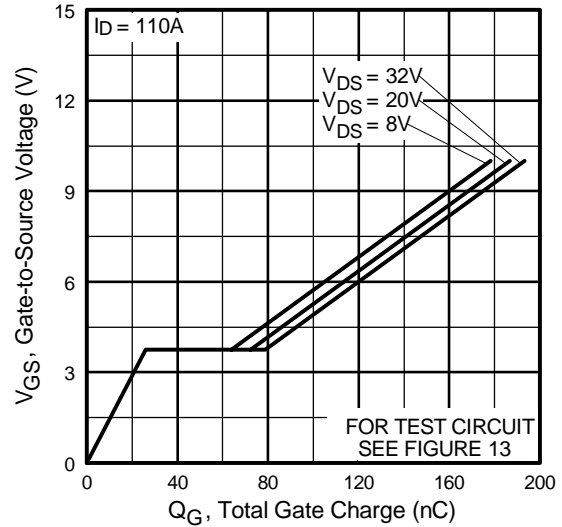
**Fig 4.** Normalized On-Resistance Vs. Temperature

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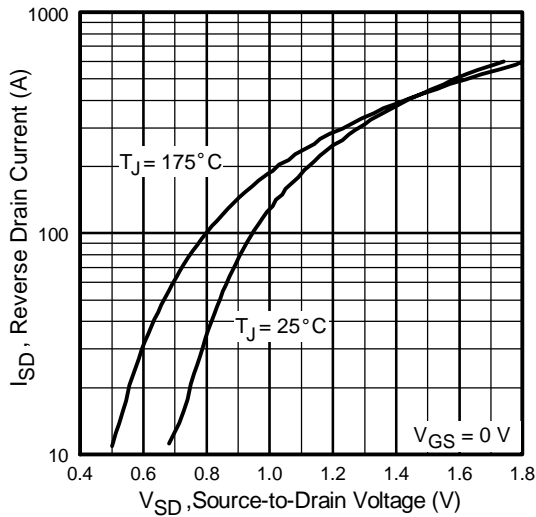
International  
**IR** Rectifier



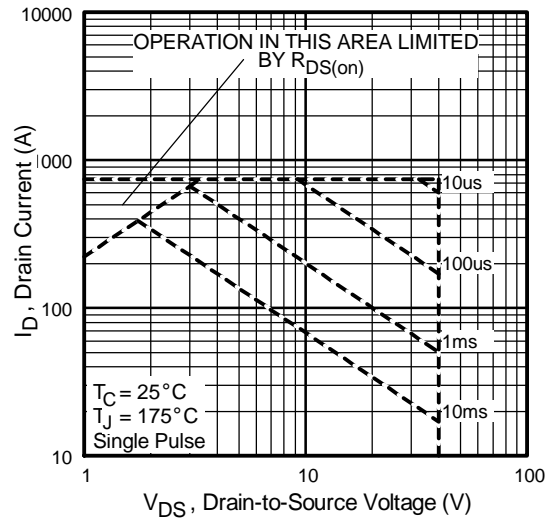
**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



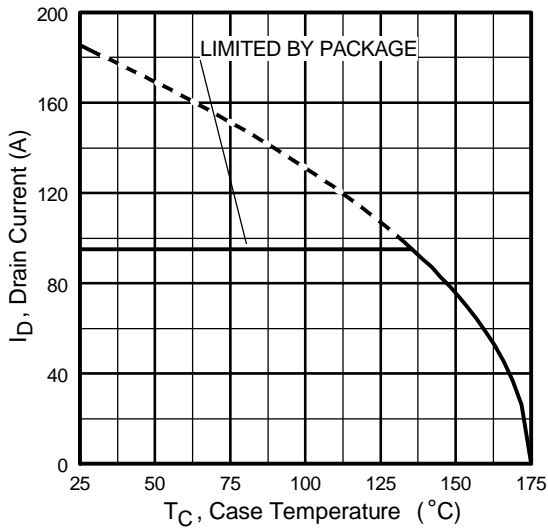
**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



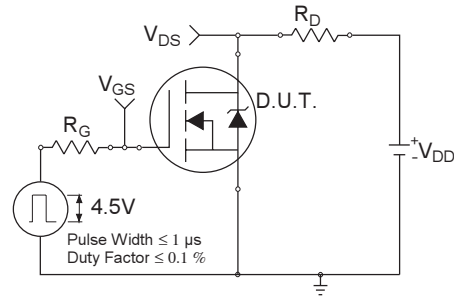
**Fig 7.** Typical Source-Drain Diode Forward Voltage



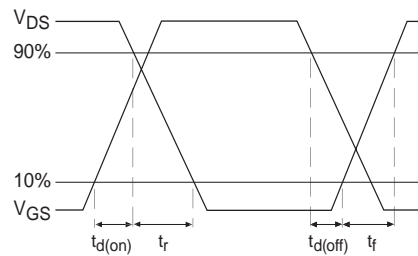
**Fig 8.** Maximum Safe Operating Area



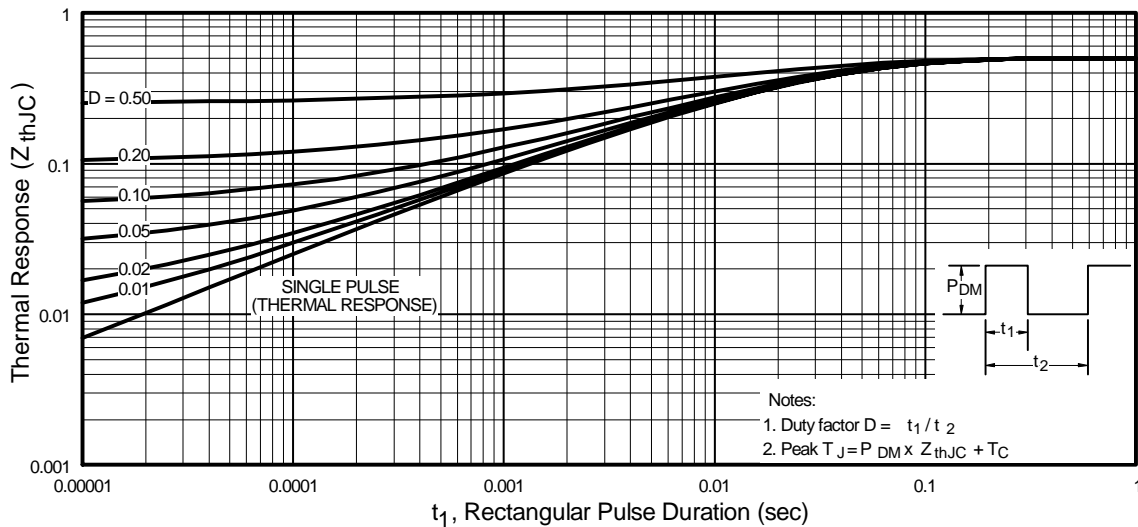
**Fig 9.** Maximum Drain Current Vs. Case Temperature



**Fig 10a.** Switching Time Test Circuit



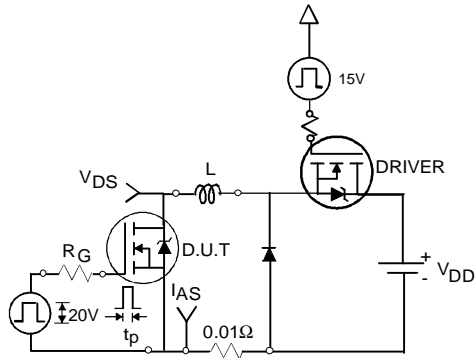
**Fig 10b.** Switching Time Waveforms



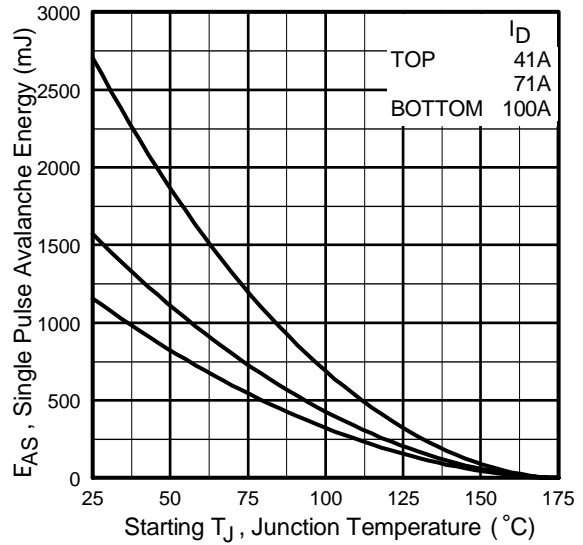
**Fig 11.** Maximum Effective Transient Thermal Impedance, Junction-to-Case

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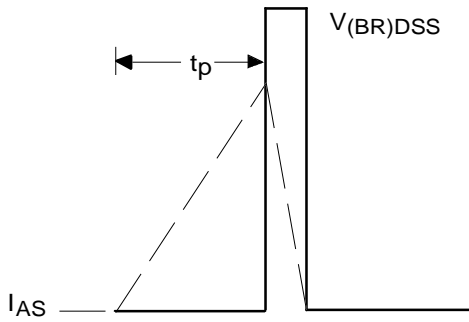
International  
**IR** Rectifier



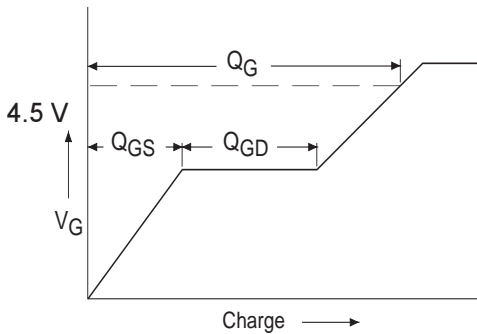
**Fig 12a.** Unclamped Inductive Test Circuit



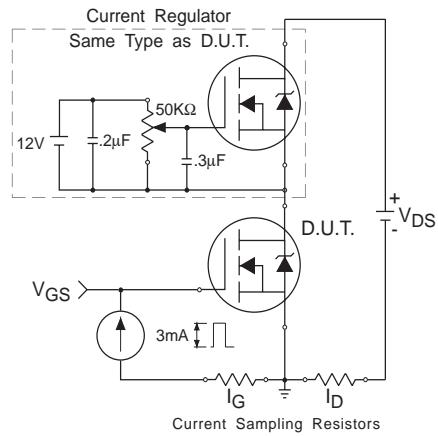
**Fig 12c.** Maximum Avalanche Energy Vs. Drain Current



**Fig 12b.** Unclamped Inductive Waveforms

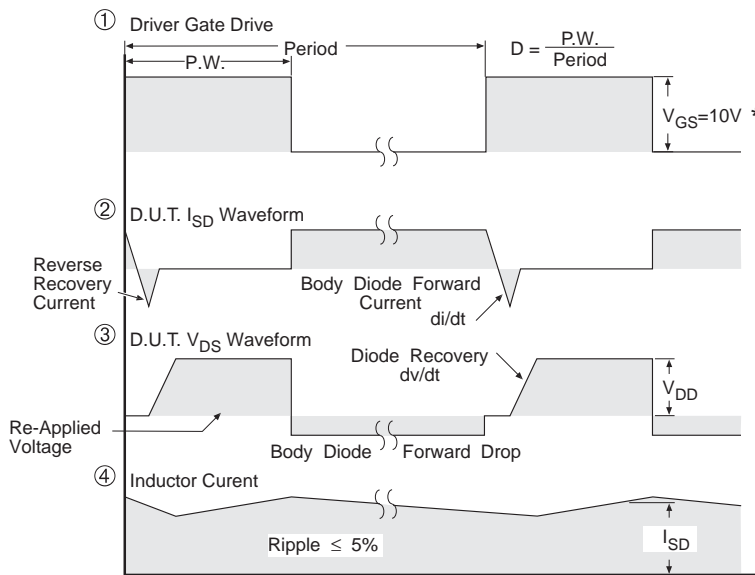
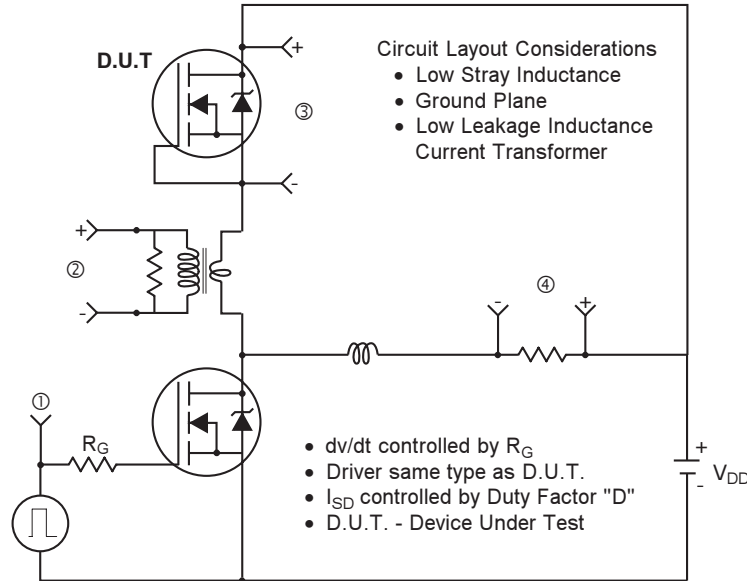


**Fig 13a.** Basic Gate Charge Waveform



**Fig 13b.** Gate Charge Test Circuit

**Peak Diode Recovery dv/dt Test Circuit**



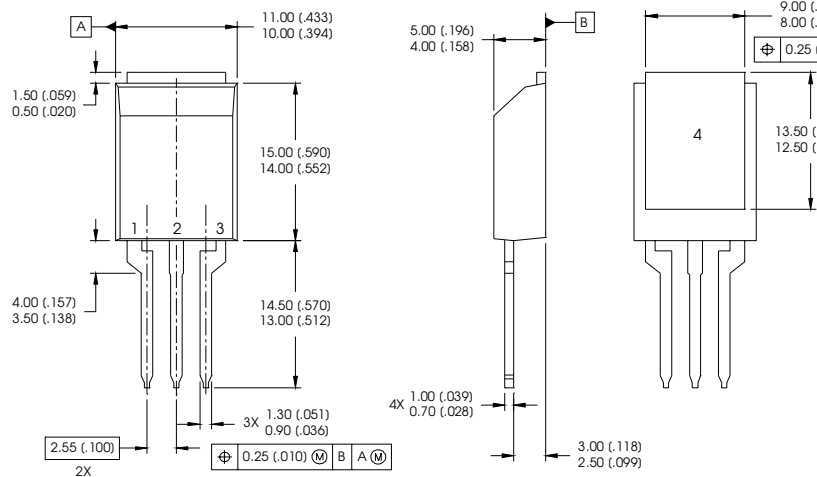
\*  $V_{GS} = 5V$  for Logic Level Devices

**Fig 14.** For N-Channel HEXFETS

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International  
**IR** Rectifier

## Super-220™ ( TO-273AA ) Package Outline



**NOTES:**

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE TO-273AA.

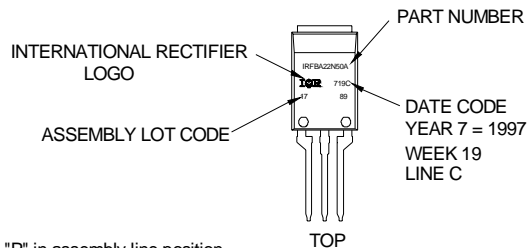
**LEAD ASSIGNMENTS**

**MOSFET**

- |            |               |
|------------|---------------|
| 1 - GATE   | 1 - GATE      |
| 2 - DRAIN  | 2 - COLLECTOR |
| 3 - SOURCE | 3 - EMITTER   |
| 4 - DRAIN  | 4 - COLLECTOR |

## Super-220 (TO-273AA) Part Marking Information

EXAMPLE: THIS IS AN IRFBA22N50A WITH  
ASSEMBLY LOT CODE 1789  
ASSEMBLED ON WW 19, 1997  
IN THE ASSEMBLY LINE "C"



Note: "P" in assembly line position indicates "Lead-Free"

Data and specifications subject to change without notice.

International  
**IR** Rectifier

**IR WORLD HEADQUARTERS:** 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
TAC Fax: (310) 252-7903

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